# Equipment Information Sheet Objet30 Pro 3D Printer

Manager: Xinwei Wu607-254-4934Calls to staff phones will be automatically forwarded to<br/>their cell phones during accessible hours. At other times<br/>leave a message or send them an email.

#### SAFETY

- Avoid skin contact with liquid polymers
- Avoid fumes and particulates from processes materials
- Avoid staring directly at the UV light during printing
- The furnaces are run at elevated temperatures of 400-1200°C and use flammable, toxic, and corrosive gases.

# USAGE RESTRICTIONS SCHEDULING/SIGN-UP RESTRICTIONS

Minimum Tool Time: 20 minutes

• Reservation blocks greater than 8 hrs must be cleared by a MOS staff person prior to reserving the time

# MATERIALS COMPATIBILITY CATEGORY

### **Tool Category 5: Class A and B Metals and Compounds**

Allowed	Not Allowed
Tool category 1/1E, 2, 3, and 4 materials	
Silicon Based Substrates and Films	
III/V compound Semiconductors	
Glass Substrates	
PECVD and ALD Films	
Cured organics and baked Photoresist	
CNF Class A, B, and Refractory metals	
Exposed Gold, Silver, Copper	
Alkali and Alkaline Compounds	
Organic/Biology Molecules prepared- w/salt buffers	
High Vapor Pressure Materials (Mg, Ca, Zn)*	* Some tool restrictions on high vapor pressure materials may apply
Soft organic materials	

# High Vapor Pressure Metals and Compounds are materials that have a vapor pressure above 1e-6 Torr at 400 C.

## **Additional Material Restrictions and Exceptions**

- Choose from 3 supplied polymers (DurusWhite, VeroClear, or RGD525)
- Use only water with Dawn dish soap to soak devices
- MOS CLEAN furnaces
- Silicon wafers, electronic grade SiC, or pure fused silica/quartz samples only
- No glass substrates, compound semiconductors, etc.
- No resists, polymers, or metals---exposed or unexposed
- Only samples with MOS and PECVD films ar